

IN THE CLAIMS

Please amend the claims as follows.

sub
C1
14. (Twice Amended) An apparatus comprising:
a first substrate with a semiconductor film formed thereon;
wherein said semiconductor film is demarcated from a rest of said first
substrate by a damaged surface, with the damaged surface being removed; and
a second substrate with a metal film formed thereon, said second substrate
bonded with the metal film to said semiconductor film of said first substrate].

C2
17. (Amended) The apparatus of claim [14] 24 wherein said metal film includes a
noble metal.

C3
19. (Amended) The apparatus of claim [14] 24 wherein said metal film is formed
on a second film of oxide formed on said second substrate.

C4
20. (Twice Amended) An apparatus comprising:
a substrate;
a first oxide film formed on said substrate;
a metal film formed on said first oxide film;
the first oxide film debonds the metal film from the substrate;
a second oxide layer formed on said metal film; [and]
a semiconductor film formed on said second oxide film, said semiconductor
film having [a least one active device formed therein] a first level of